Single Inverter with Schmitt Trigger

The NL17SZ14 is a single inverter with Schmitt trigger in two tiny footprint packages. The device performs much as LCX multi-gate products in speed and drive.

Features

- Tiny SOT-353 and SOT-553 Packages
- Source/Sink 24 mA at 3.0 V
- Over–Voltage Tolerant Inputs and Outputs
- Pin For Pin with NC7SZ14
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Chip Complexity: FET = 20
- Pb–Free Packages are Available

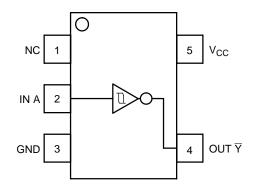


Figure 1. Pinout



Figure 2. Logic Symbol



ON Semiconductor®

http://onsemi.com

MARKING DIAGRAMS





SOT-353/SC70-5/SC-88A **DF SUFFIX CASE 419A**





SOT-553 **XV5 SUFFIX** CASE 463B

- Μ = Date Code*
- = Assembly Location Α Υ
 - = Year
- W = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT				
1	NC			
2	IN A			
3	GND			
4	OUT Y			
5	V _{CC}			

A Input	Y Output
L	H
H	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Charac	cteristics	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		$-0.5 \leq V_{I} \leq +7.0$	V
Vo	DC Output Voltage	Output in High or LOW State (Note 1)	$-0.5 \le V_O \le 7.0$	V
I _{IK}	DC Input Diode Current	V _I < GND	- 50	mA
Ι _{ΟΚ}	DC Output Diode Current	V _O < GND	- 50	mA
Ι _Ο	DC Output Sink Current		± 50	mA
I _{CC}	DC Supply Current per Supply Pin		±100	mA
I _{GND}	DC Ground Current per Ground Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
PD	Power Dissipation in Still Air	SOT-353 SOT-553	186 135	mW
θ_{JA}	Thermal Resistance	SOT-353 SOT-553	350 496	°C/W
ΤL	Lead Temperature, 1 mm from Case for	or 10 Seconds	260	°C
TJ	Junction Temperature under Bias		+ 150	°C
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V–0 @ 0.125 in	
ESD	ESD Classification	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	Class 2 Class C N/A	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.
1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
2. Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.

3. Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.

4. Tested to JESD22-C101-A.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Мах	Unit
V _{CC}	Supply Voltage	Operating Data Retention Only	1.65 1.5	5.5 5.5	V
VI	Input Voltage		0	5.5	V
Vo	Output Voltage	(High or LOW State)	0	5.5	V
T _A	Operating Free-Air Temperature		- 40	+ 85	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate	$\begin{array}{l} {\sf V}_{CC} = 2.5 \ {\sf V} \ \pm 0.2 \ {\sf V} \\ {\sf V}_{CC} = 3.0 \ {\sf V} \ \pm 0.3 \ {\sf V} \\ {\sf V}_{CC} = 5.0 \ {\sf V} \ \pm 0.5 \ {\sf V} \end{array}$	0 0 0	No Limit No Limit No Limit	ns/V

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	T _A	= 25°C		$-40^{\circ}C \le T_A \le 85^{\circ}C$		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
$V_T +$	Positive Input		1.65	0.6	1.0	1.4	0.6	1.4	V
	Threshold Voltage		2.3	1.0	1.5	1.8	1.0	1.8	
			2.7	1.2	1.7	2.0	1.2	2.0	
			3.0	1.3	1.9	2.2	1.3	2.2	
			4.5	1.9	2.7	3.1	1.9	3.1	
			5.5	2.2	3.3	3.6	2.2	3.6	
V _T -	Negative Input		1.65	0.2	0.5	0.8	0.2	0.8	V
	Threshold Voltage		2.3	0.4	0.75	1.15	0.4	1.15	
			2.7	0.5	0.87	1.4	0.5	1.4	
			3.0	0.6	1.0	1.5	0.6	1.5	
			4.5	1.0	1.5	2.0	1.0	2.0	
			5.5	1.2	1.9	2.3	1.2	2.3	
V _H	Input Hysteresis Voltage		1.65	0.1	0.48	0.9	0.1	0.9	V
			2.3	0.25	0.75	1.1	0.25	1.1	
			2.7	0.3	0.83	1.15	0.3	1.15	
			3.0	0.4	0.93	1.2	0.4	1.2	
			4.5	0.6	1.2	1.5	0.6	1.5	
			5.5	0.7	1.4	1.7	0.7	1.7	
V _{OH}	High-Level Output	I _{OH} = -100 μA	1.65 to 5.5	V _{CC} – 0.1	V _{CC}		V _{CC} – 0.1		V
	Voltage V _{IN} = V _{IH} or V _{IL}	I _{OH} = -3 mA	1.65	1.29	1.52		1.29		
		$I_{OH} = -8 \text{ mA}$	2.3	1.9	2.1		1.9		
		$I_{OH} = -12 \text{ mA}$	2.7	2.2	2.4		2.2		
		$I_{OH} = -16 \text{ mA}$	3.0	2.4	2.7		2.4		
		$I_{OH} = -24 \text{ mA}$	3.0	2.3	2.5		2.3		
		$I_{OH} = -32 \text{ mA}$	4.5	3.8	4.0		3.8		
V _{OL}	Low-Level Output	I _{OL} = 100 μA	1.65 to 5.5		0.0	0.1		0.1	V
	Voltage V _{IN} = V _{IH} or V _{IL}	I _{OL} = 4 mA	1.65		0.08	0.24		0.24	
		I _{OL} = 8 mA	2.3		0.2	0.3		0.3	
		I _{OL} = 12 mA	2.7		0.22	0.4		0.4	
		I _{OL} = 16 mA	3.0		0.28	0.4		0.4	
		I _{OL} = 24 mA	3.0		0.38	0.55		0.55	
		I _{OL} = 32 mA	4.5	1	0.42	0.55	1	0.55	
I _{IN}	Input Leakage Current	$V_{IN} = V_{CC} \text{ or } GND$	0 to 5.5	1		±0.1	1	±1.0	μΑ
I _{OFF}	Power Off–Output Leakage Current	V _{OUT} = 5.5 V	0			1		10	μΑ
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1		10	μΑ

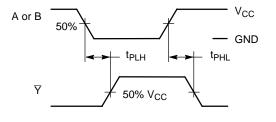
AC ELECTRICAL CHARACTERISTICS t_{R} = t_{F} = 3.0 ns

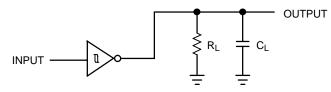
			V _{CC}	T _A = 25°C		$-40^\circ C \leq T_A \leq 85^\circ C$			
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Мах	Unit
t _{PLH} t _{PHL}	Propagation Delay (Figure 3 and 4)	$R_L = 1 M\Omega, C_L = 15 pF$	$\begin{array}{c} 1.65 \\ 1.8 \\ 2.5 \pm 0.2 \\ 3.3 \pm 0.3 \\ 5.0 \pm 0.5 \end{array}$	2.0 2.0 1.0 1.0 0.5	9.1 7.6 5.0 3.7 3.1	15 12.5 9.0 6.3 5.2	2.0 2.0 1.0 1.0 0.5	15.6 13 9.5 6.5 5.5	ns
		R_L = 500 Ω, C_L = 50 pF	$\begin{array}{l} 3.3\ \pm\ 0.3\\ 5.0\ \pm\ 0.5\end{array}$	1.5 0.8	4.4 3.7	7.2 5.9	1.5 0.8	7.5 6.2	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	$V_{CC} = 5.5 \text{ V}, \text{ V}_{I} = 0 \text{ V or } V_{CC}$	>4.0	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	10 MHz, $V_{CC} = 3.3 \text{ V}$, $V_I = 0 \text{ V}$ or V_{CC} 10 MHz, $V_{CC} = 5.5 \text{ V}$, $V_I = 0 \text{ V}$ or V_{CC}	25 30	pF

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.





A 1–MHz square input wave is recommended for propagation delay tests.

Figure 3. Switching Waveform

Figure 4. Test Circuit

DEVICE ORDERING INFORMATION

Device Order Number	Package Type	Tape and Reel Size [†]
NL17SZ14DFT2	SOT-353/SC70-5/SC-88A	3000 / Tape & Reel
NL17SZ14DFT2G	SOT-353/SC70-5/SC-88A (Pb-Free)	3000 / Tape & Reel
NL17SZ14XV5T2	SOT-553*	3000 / Tape & Reel
NL17SZ14XV5T2G	SOT-553*	3000 / Tape & Reel

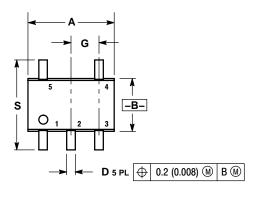
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

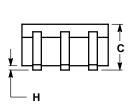
*All Devices in Package SOT553 are Inherently Pb-Free.

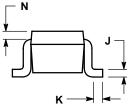
NL17SZ14

PACKAGE DIMENSIONS

SC-88A, SOT-353, SC-70 CASE 419A-02 ISSUE J



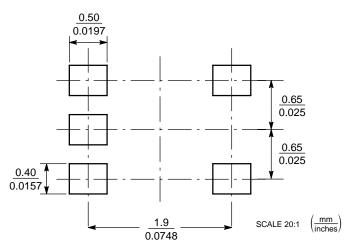




NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02. 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	0.026 BSC		BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

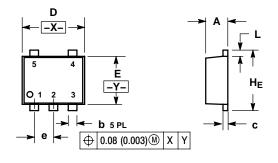
SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOT-553, 5 LEAD CASE 463B-01 ISSUE B

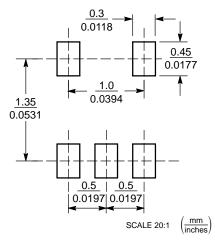


NOTES

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS 3. MAXIMUM LEAD THICKNESS INCLUDES 1 FAD FINISH THICKNESS, MINIMUM LEAD
- LEAD THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS				INCHES			
DIM	MIN	NOM	MAX	MIN NOM MA				
Α	0.50	0.55	0.60	0.020	0.022	0.024		
b	0.17	0.22	0.27	0.007	0.009	0.011		
С	0.08	0.13	0.18	0.003	0.005	0.007		
D	1.50	1.60	1.70	0.059	0.063	0.067		
Е	1.10	1.20	1.30	0.043	0.047	0.051		
e		0.50 BSC		0.020 BSC				
L	0.10	0.20	0.30	0.004	0.008	0.012		
HE	1.50	1.60	1.70	0.059	0.063	0.067		

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and use registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other application is unich the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use personal and such apglication the design or manufacture of the part. SCILLC is an Equal Opportunit/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082–1312 USA Phone: 480–829–7710 or 800–344–3860 Toll Free USA/Canada Fax: 480–829–7709 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2–9–1 Kamimeguro, Meguro–ku, Tokyo, Japan 153–0051 Phone: 81–3–5773–3850 ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.

NL17SZ14/D